



Advanced Knowledge and Modelling of Welded Materials for Ultrasonic Testing

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Deadline for manuscript
submissions:

closed (25 May 2023)

Message from the Guest Editor

The purpose of this Special Issue of *Applied Sciences* (IF: 2.474) is to bring together advanced developments on the ultrasonic testing of welded material and state-of-the-art knowledge on welded material. All welding processes are studied including additive manufacturing (AM) such as wire-arc AM. This Special Issue welcomes research papers aiming to ally material sciences and NDT science and to share knowledge and advances on this topic. The final goal is to assess mechanical integrity so Artificial Intelligence developments to improve UT testing of welds are also highly welcome.

We invite prospective authors to submit innovative and high-quality papers with original perspectives. The Special Issue is open to both original research articles and review articles covering all the relevant progress in these fields (including but not limited to the following):

- Weld material description;
- Materials vs. welding process;
- Additive manufacturing
- Modelling ultrasonic testing;
- Hybrid modelling;
- Attenuation and deviation of waves
- Phased arrays UT
- Inverse problems
- Artificial Intelligence





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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